

HOSTAFORM® SXT90Z-02 XAP®

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Hostaform® acetal copolymer grade SXT90Z-02 XAP® is a UV stabilized, impact modified material available in a range of colors for automotive interior applications, while also meeting the typical low emission requirements of the automotive market. Chemical abbreviation according to ISO 1043-1: POM-HI Low emission performance (VDA 275) < 10 ppm

Product information

Resin Identification	(POM+TPU)	ISO 1043
Part Marking Code	>(POM+TPU)<	ISO 11469

Rheological properties

Melt volume-flow rate	4 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile modulus	1500 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	41 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	13 %	ISO 527-1/-2
Flexural modulus	1450 MPa	ISO 178
Flexural stress at 3.5%	40 MPa	ISO 178
Charpy impact strength, 23°C	N kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	N kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	13 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	8 kJ/m ²	ISO 179/1eA
Poisson's ratio	0.43 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	65 °C	ISO 75-1/-2

Physical/Other properties

Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1360 kg/m ³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C
Min. melt temperature	180 °C
Max. melt temperature	200 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	65 °C
Min. mould temperature	60 °C
Max. mould temperature	70 °C
Hold pressure range	60 - 120 MPa

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Back pressure

2 MPa

Characteristics

Processing

Injection Moulding

Special characteristics

High impact or impact modified, U.V. stabilised or stable to weather, Low emissions

Additional information

Processing Notes

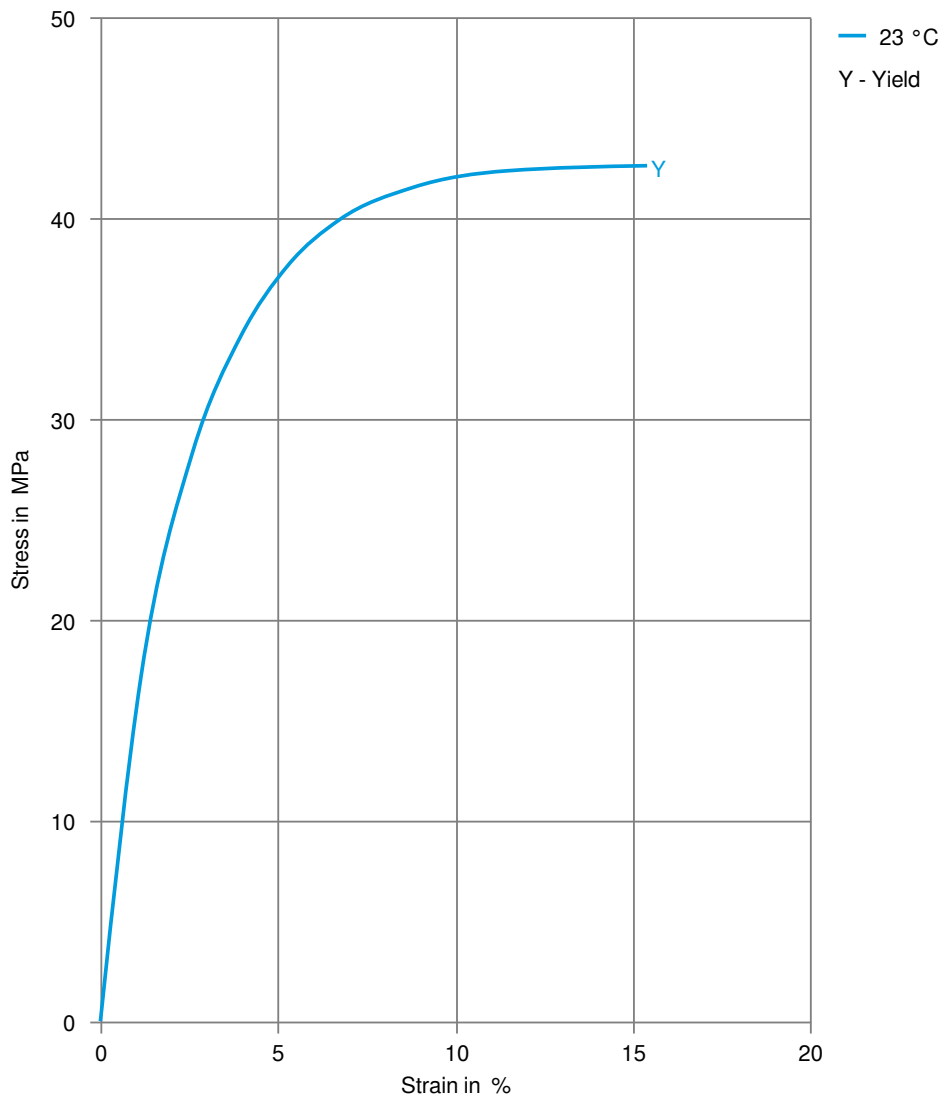
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying to prevent splay and odor problems.

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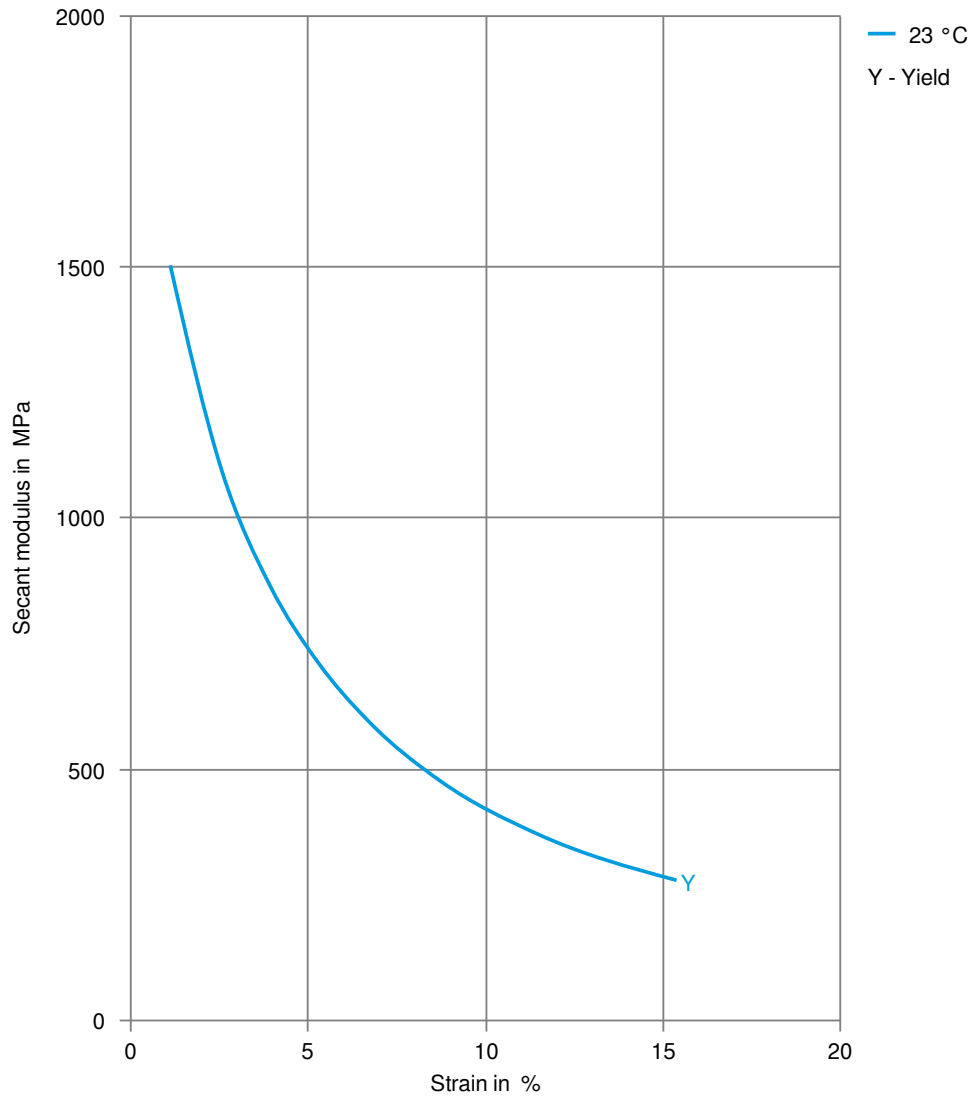
Stress-strain



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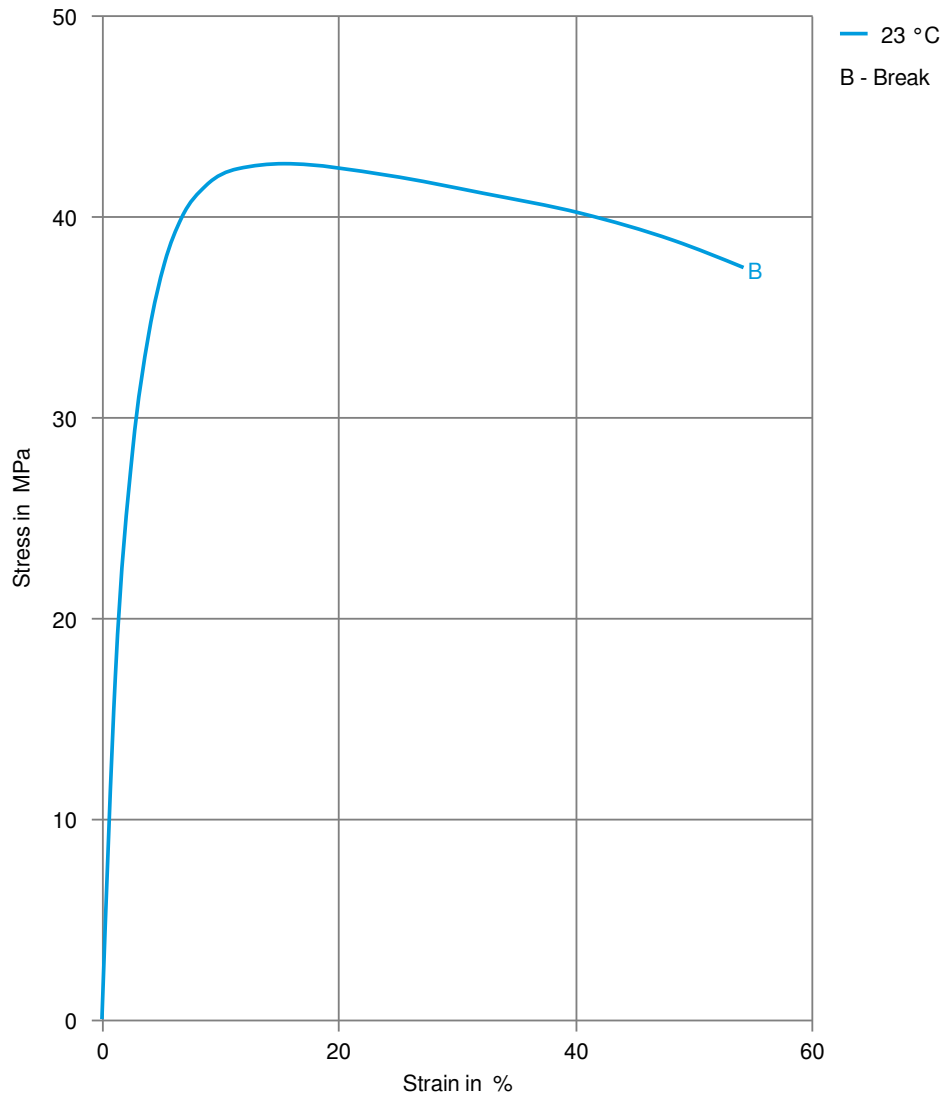
Secant modulus-strain



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Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min

